ePTM Series

Description :

ePTMseries is the first e-beam hotspot process monitoring inspection system. ePTM3xp offers highest detection sensitivity to electrical and physical defects suitable for both early R&D and in-line monitoring in mass production fabs. ePTM3xp's leading-edge image resolution and LFOV (Large Field of View) enables effective pattern verification application such as OPC error and CDU measurement.

ePTM Series

Value Proposition :

- An e-beam hotspot/weak-point process monitoring system with high throughput.
- An e-beam hotspot/weak-point process monitoring system that enables quick characterization of full wafer property.
- An e-beam hotspot/weak-point process monitoring system offers the highest VC and physical sensitivity.
- An e-beam hotspot/weak-point process monitoring system with the lowest CoO.
- An e-beam system with capability to measure CDU on an array of 2D structures, such as gate and AA of SRAM array.
- The eManagerTM ADC system with the most advanced defect binning algorithm.

Applications :

ePTM series handles systematic variation of electrical and physical properties on the wafer surface. The typical application includes contact non-open, OPC error, piping, bridge, broken line and more for hotspot /weak-point processes monitoring. It is also very useful for defect inspection and characterization at early stage of R&D when defect density is very high. 2D CDU capability could allow customers to quickly identify the center of the photolithography process window.